

DA22F21

Silicon epitaxial planar type

For high speed switching circuits

■ Features

- Short reverse recovery time t_{rr}
- Low impedance by clip bonding package
- Contributes to miniaturization of sets, mount area reduction
- Eco-friendly Halogen-free package

■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Package

- Code
Mini2-F4-B
- Pin Name
1: Cathode
2: Anode

■ Marking Symbol: 3Q

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|---|-----------|-------------|------|
| Repetitive peak reverse voltage | V_{RRM} | 200 | V |
| Non-repetitive peak reverse surge voltage | V_{RSM} | 200 | V |
| Forward current | I_F | 1.0 | A |
| Non-repetitive peak forward surge current * | I_{FSM} | 15 | A |
| Junction temperature | T_j | -40 to +150 | °C |
| Storage temperature | T_{stg} | -40 to +150 | °C |

Note) *: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

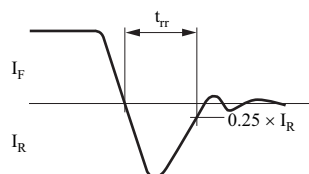
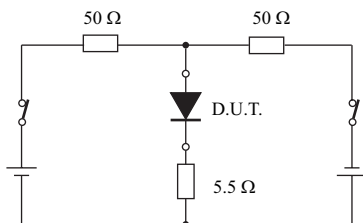
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

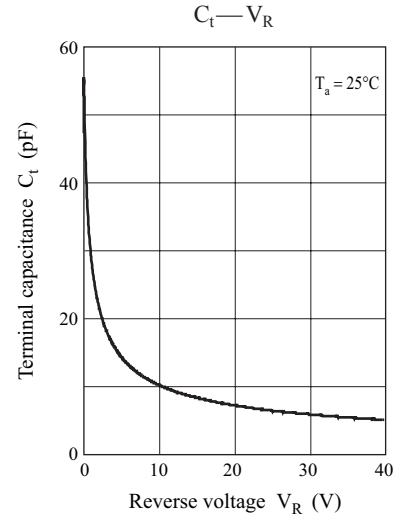
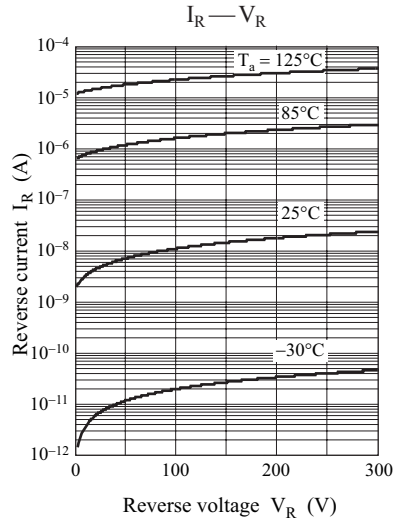
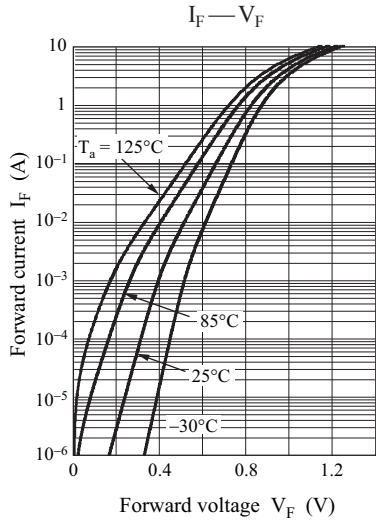
| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|-------------------------|-----------|--|-----|-----|------|---------------|
| Forward voltage | V_F | $I_F = 1.0 \text{ A}$ | | | 0.98 | V |
| Reverse current | I_{RRM} | $V_{RRM} = 200 \text{ V}$ | | | 10 | μA |
| Terminal capacitance | C_t | $V_R = 0 \text{ V}, f = 1 \text{ MHz}$ | | 60 | | pF |
| Reverse recovery time * | t_{rr} | $I_F = 0.5 \text{ A}, I_R = 1 \text{ A}, I_{tr} = 0.25 \times I_R$ | | | 35 | ns |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

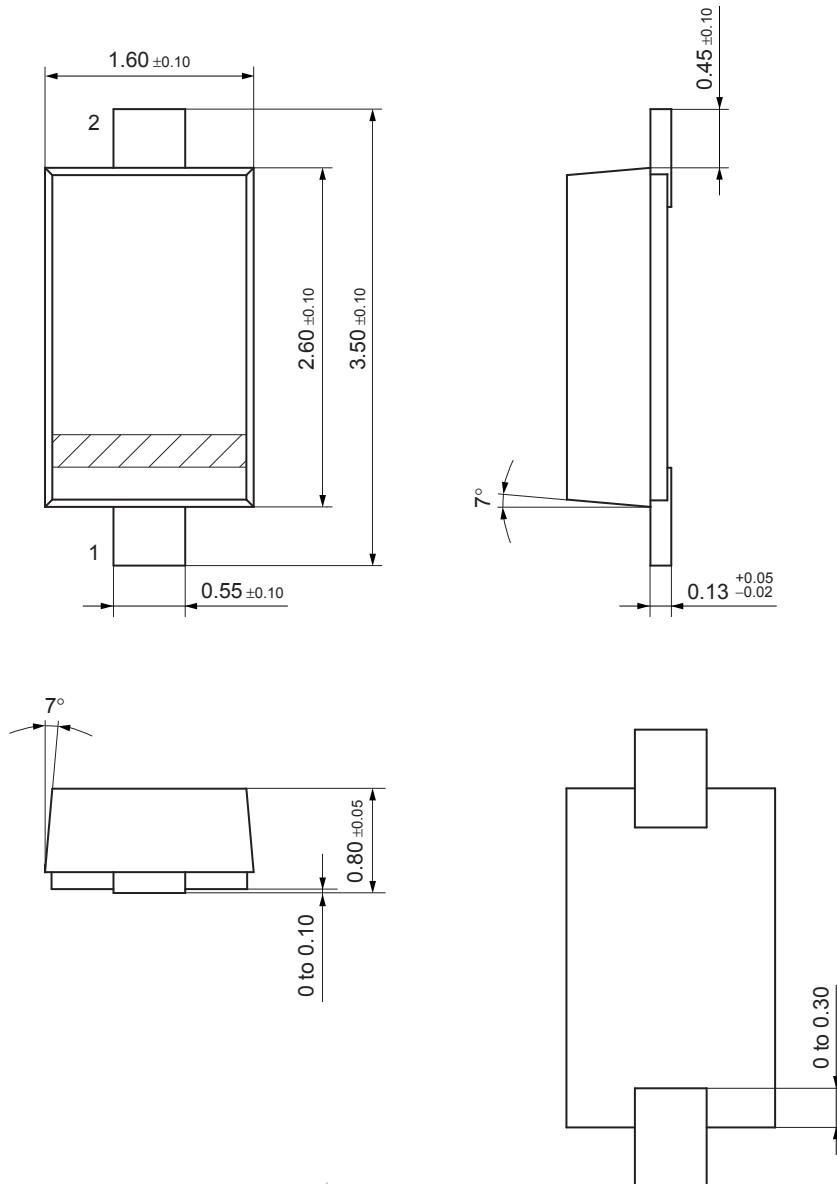
3. *: t_{rr} measurement circuit





Mini2-F4-B

Unit: mm



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